

CALIFORNIA STATE SCIENCE FAIR 2015 PROJECT SUMMARY

Name(s)	Project Number
Omkar A. Salpekar	
	35495
Project Title	$\hat{\boldsymbol{\mathcal{C}}}$
Improved Integrated Circuit Performance by Geometrically Optimized Tri-Gate FinFETs	
	$\sim \sqrt{2}$
Objectives/Goals Abstract	
As the technology node gets scaled down aggressively, it is well known that by	CMDS transistors leak
prohibitive amounts of current. Furthermore, capacitive elements in the bulk C	NOS substrate channel
increase propagation delay. FinFET transistors resolve this with a comparative However, to achieve even better leakage and delay values, FinFETT's greater ve	ly fower leakage current.
CMOS, which increases its parasitic capacitance, is a hindrance.	on the compared to bulk
CMOS, which increases its parasitic capacitance, is a hindrance. This work tries to optimize the geometry of FinFET structure and this tries to	ower the leakage even
further by lowering capacitance.	
Methods/Materials BSIM's EinFET models were used for experimentation and ideal values of values	les for various FinEET
BSIM's FinFET models were used for experimentation and ideal ranges of valu structural parameters were obtained. A separate FinFET model was coded to all	low greater flexibility in
optimization, and the data from the two was compared A NAR modeling too	l was also used for
non-mathematical electrical simulations.	
Results	pariments. Results obtained
It was taken care that the performance of the device is not degraded in these experiments. Results obtained are encouraging and can serve as a guideline for realizing new and better derivatives of FinFET.	
Conclusions/Discussion	
In general, smaller technology nodes displayed the best performance, and substrate capacitance is	
typically minimal, so the pitch between components must be decreased. With on-state current flowing	
along the fin's edges and off-state current flowing through the fin's center, decreasing fin thickness should maintain performance while increasing energy efficiency. Finally, increased fin height does not affect parasitic capacitance appreciably but it does increase propagation delay, thus the tradeoff ideal range for	
parasitic capacitance appreciably but i does increase propagation delay, thus the	tradeoff ideal range for
fin height lies at around 43-47nm.	
Summary Statement	
My work aimed to determine the ideal structure and geometry for the Tri-Gate FinFET in order to	
decrease current leakage, propagation delay, and parasitic capacitance while maintaining on-state current.	
Help Received	
Participant in Summer Research Program at UC Santa Barbara where I worked under Mr. Shrikant Kulkarni, who was part of Dr. Kaustav Banerjee's Microelectronics Group	
Kulkalin, who was part of Dr. Kaustav Daherjee's whereeteen ones Group	